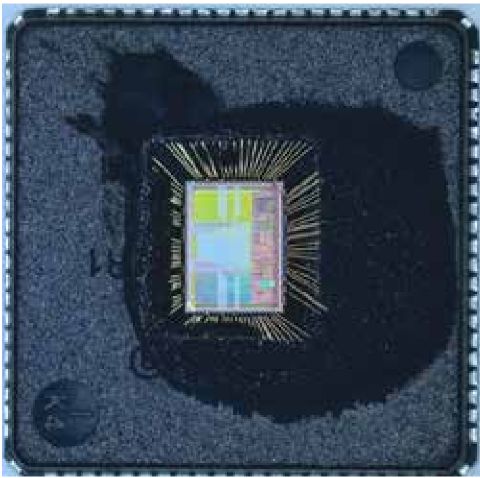
eurofins | EAG Laboratories

PICTURE BOOK

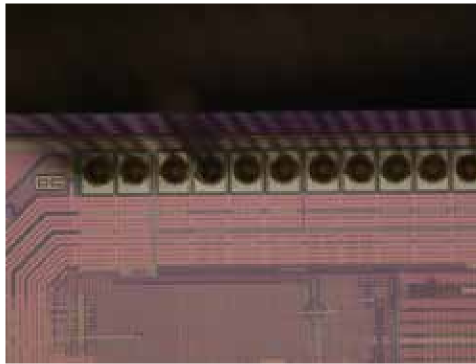
Decap Services at EAG

Decap services at EAG involve wet chemical etches to remove the plastic encapsulant on devices to allow inspection of the die. These involve precavitation by laser followed by the use of various acid solutions. Devices with aluminum or gold bond wires are standard and those with copper wires require a more involved process. Devices may be decapped individually or while mounted on a PCB.

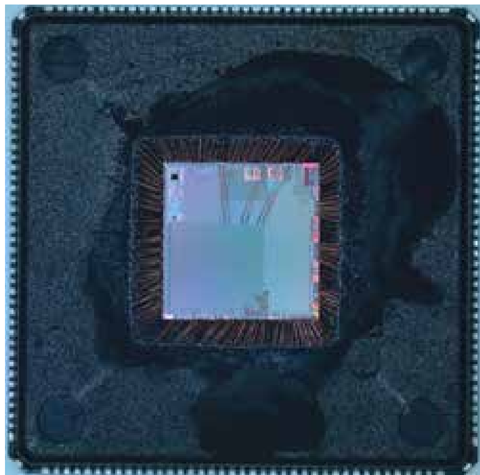
DECAP OF AU BOND WIRE DEVICE



CLOSE UP OF THE PADS



DECAP OF CU BOND WIRE DEVICE



CLOSE UP OF THE PADS

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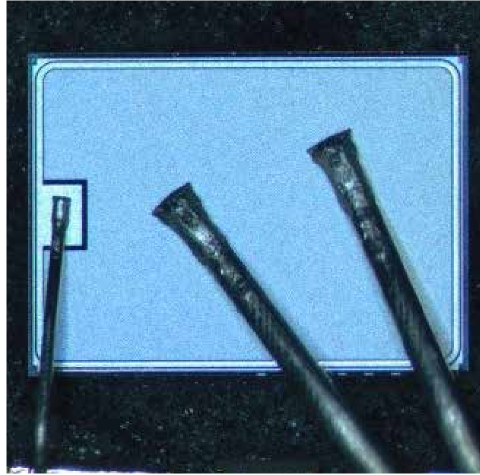
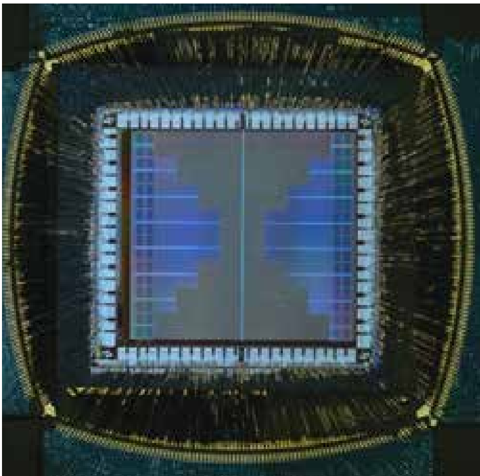
Decap Services at EAG

DECAP OF DEVICE WITH AL BOND WIRES



CLOSE UP OF WIRE ATTACH

DECAP WITH LEAD FINGERS EXPOSED



CLOSE UP OF LEAD FINGERS

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